



GE rugged COM Express Modules excel in challenging environments

GE COM Express modules are designed for OEMs developing computing platforms for equipment targeted at industrial or harsh environments, and for whom reducing the overall design cycle and lowering validation costs are of key importance.

GE Intelligent Platforms rugged COM Express modules offer outstanding reliability in a broad range of performance-per-watt options.

Our rugged processing solutions deliver leading edge performance, provide low total cost of ownership, offer flexible options, and are backed by GE's commitment to customer success.

Best-in-class performance and reliability

GE understands that processors deployed in harsh environments need to not only deliver excellent performance in relation to their power consumption, but also to deliver optimum reliability in the most adverse of operating environments. Our COM Express products are engineered specifically to meet those needs.

Onboard components are specifically selected for their reliability in demanding conditions. Unlike solutions designed for benign environments, our processor and memory are soldered to the board for maximum resistance to shock and vibration.

Extended mechanical construction protects the module, which is designed for optional conformal coating for even greater resistance to moisture, dust, chemicals, and temperature extremes.

As such, GE is uniquely positioned to enable our customers to meet the exacting requirements of critical infrastructure applications.

We are equally committed to ensuring that our customers can leverage the unique benefits of the COM Express architecture by designing modules in line with the newest processor architectures, providing a simple, cost-effective upgrade path.

Longer lifecycles and lower product costs

The COM Express architecture separates the processor and carrier card, extending the useful life of the subsystem by allowing a cost-effective upgrade of the processor alone. The long-term cost of ownership is

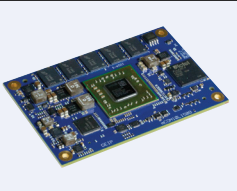
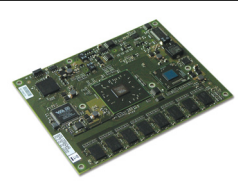
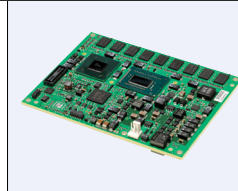

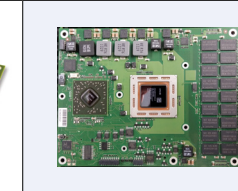
reduced while ensuring that performance keeps pace with changing needs.

Commitment to customer satisfaction

Today's organizations are operating lean, engineering resources are scarce, and time-to-market is critical. Therefore, GE complements the performance and practical benefits of our COM Express modules with leading domain expertise and a focus on exceptional customer service. To help you get to market faster and lower your development costs, GE can assist you with in-house carrier design work, or build a custom carrier specifically for you.

"We are elated that GE has once again turned to AMD Embedded Solutions to power their high performance COM Express platform targeting ruggedized Industrial, conventional military and aerospace applications. The modular design, based on open standards, is ideally suited for next generation Industrial PCs, and will provide a path for automation controller system solution providers to scale in design based on AMD technology in those demanding environments."

Sameer Gupta
Marketing Manager, Industrial Controls and Automation
AMD Embedded Solutions

					
Product	mCOM10-L1500	bCOM6-L1200	bCOM6-L1400	bCOM6-P1100	bCOM6-L1700
Performance	Mini format, Mid-level, power saving	Mid-level performance	High-performance	Power saving	Mid to High-performance
Select for:	Applications or upgrades with mid-level performance and high graphics requirements	Applications with mid-level performance and low-power consumption requirements	Applications with multiple graphic functions that require high performance	Real-time embedded computing applications that require low power consumption and the best performance/power ratio	Applications with mid to high-level performance needs coupled with high graphics performance
Processor	AMD Embedded G-Series SOC	VIA Eden or Nano processor	Intel® Core™ i7 processor	Freescaple PowerPC 1022/1013 processor	AMD RSOC dual and Quad Core at 3.3 and 2.2 GHz
Cores/Frequency	4 Core 1.5 GHz 2 Core 1 GHz	1-2 Cores/800 MHz 1.3 GHz	2-4 Cores/1.7 GHz 2.5 GHz	1-22 Cores/800 MHz 1.2 GHz	<ul style="list-style-type: none"> • 4x x86 cores @ 3.6 GHz (max) / 2.7 GHz (base) • 8x GPUs @ 686 MHz (max) / 600 MHz (base) • 2x x86 cores @ 3.0 GHz (max) / 2.2 GHz (base) • 3x GPUs @ 533 MHz (max) / 464 MHz (base)
Memory	Up to 4GB DDR3, soldered ECC	Up to 8GB DDR3, soldered, non-ECC	Up to 8GB DDR3, soldered, ECC	Up to 4GB DDR3, soldered, ECC	Up to 16GB DDR3, soldered, ECC

GE's COM Express modules are rugged enough to deliver the processing performance you need for application deployed in challenging environments. Challenge us to help you find the right GE rugged COM Express solution for your computing platform design. Contact your local representative for more information about GE's COM Express solutions.

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